

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**  
 Created on: **11/03/2020**

**Details for "TPS611781RNWR"**

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TPS611781RNWR	NIPDAU	Level-2-260C-1 YEAR	TI PHILIPPINES CLARK A/T	RNW   13	3.5x3x0.9	22.2

**\*Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	7.201773	97.585	975850	32.403616	324036
Copper and Its Alloys	Iron	7439-89-6	0.16974	2.3	23000	0.763727	7637
Copper and Its Alloys	Phosphorus	7723-14-0	0.001107	0.015	150	0.004981	50
Zinc and Its Alloys	Zinc	7440-66-6	0.00738	0.1	1000	0.033206	332
Sub-Total			<b>7.38</b>	<b>100</b>	<b>1000000</b>	<b>33.20553</b>	<b>332055</b>
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.057072	95.12	951200	0.256789	2568
Precious Metals	Gold	7440-57-5	0.000468	0.78	7800	0.002106	21
Precious Metals	Palladium	7440-05-3	0.00246	4.1	41000	0.011069	111
Sub-Total			<b>0.06</b>	<b>100</b>	<b>1000000</b>	<b>0.269964</b>	<b>2700</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	8.432583	73.499994	735000	37.941515	379415
Other Inorganic Materials	Silica	7631-86-9	1.720935	14.999996	150000	7.743165	77432
Other Plastics and Rubber	Carbon Black	1333-86-4	0.057365	0.500004	5000	0.258108	2581
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.057365	0.500004	5000	0.258108	2581
Other Plastics and Rubber	Silicone	218163-11-2	0.057365	0.500004	5000	0.258108	2581
Thermoplastics	Epoxy	85954-11-6	1.14729	9.999997	100000	5.16211	51621
Sub-Total			<b>11.472903</b>	<b>100</b>	<b>1000000</b>	<b>51.621114</b>	<b>516211</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	3.165218	100	1000000	14.241564	142416
Sub-Total			<b>3.165218</b>	<b>100</b>	<b>1000000</b>	<b>14.241564</b>	<b>142416</b>
<b>Solder Bump</b>							
Copper and Its Alloys	Copper	7440-50-8	0.129618	88.119761	881198	0.583202	5832
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.016592	11.279939	112799	0.074654	747

Precious Metals	Silver	7440-22-4	0.000883	0.6003	6003	0.003973	40
Sub-Total			<b>0.147093</b>	<b>100</b>	<b>1000000</b>	<b>0.661829</b>	<b>6618</b>
<b>Total</b>			22.225214			100	1000000

#### Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

#### Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

#### Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

#### Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

#### Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)

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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.